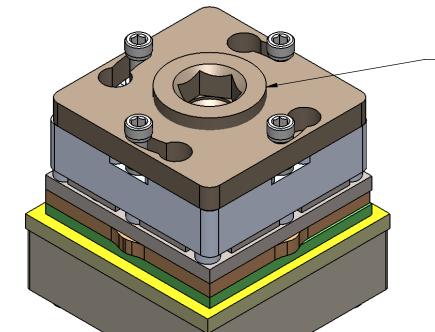
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

Features

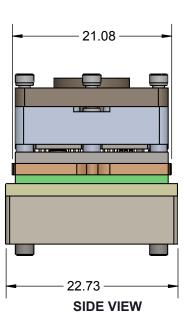
Recommended torque = 8 in-lbs

- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield Highly compliant to accommodate wide co-planarity variations Automated probe manufacturing enables low cost and short lead



21.33 12.82 9.4640 22.73

FRONT VIEW



Description: SBT-BGA 15x15mm 0.65mm pitch 22x22 array BGA396

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

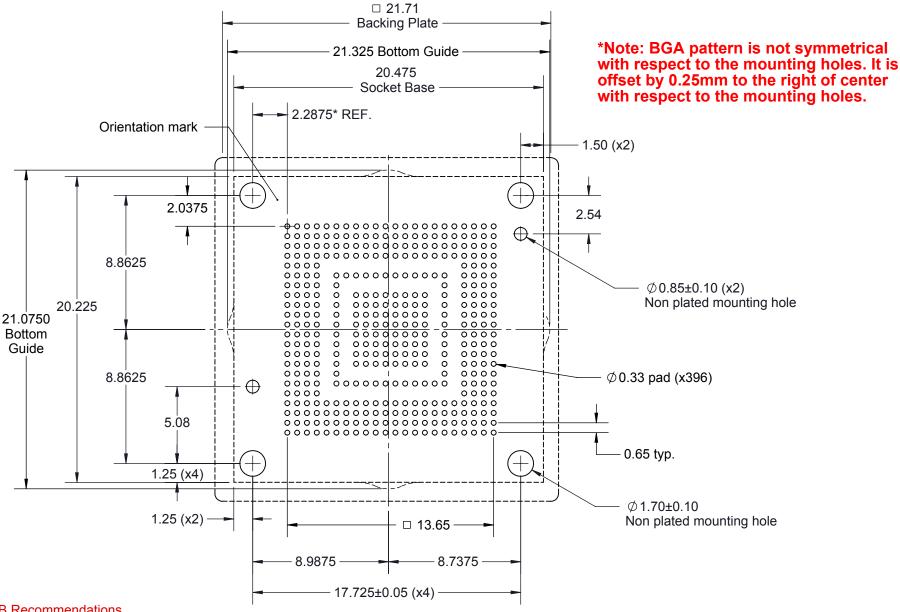
SB	Γ-BGA	-7009	Drawing	



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Material: n/a Finish: n/a Weight: 21.11

STATUS: Released	SHEET: 1 OF 5	REV. B
ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 3:1
FILE: SBT-BGA-7009 Dwg	DATE: 2/25/2013	



Target PCB Recommendations Total thickness: 1.6mm min. Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

Description: Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-7009 Drawing

©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: n/a Finish: n/a Weight: 21.11

STATUS: Released	SHEET: 2 OF 5	REV. B
ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 4:1
FILE: SBT-BGA-7009 Dwg	DATE: 2/25/2013	

A1 В С 0.10 C

DETAIL A SCALE 8:1

- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: BGA spec

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

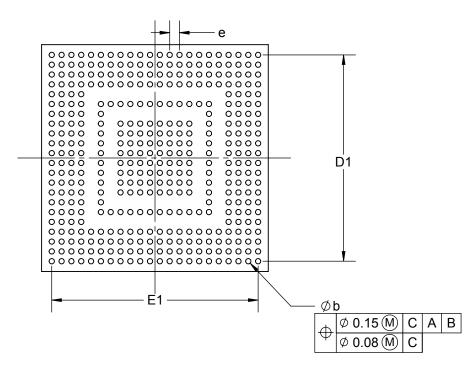
BBT-BGA-7009 Drawing	Material: n/a
©2015 Ironwood Electronics Inc	Finish: n/a

Tele: (800) 404-0204

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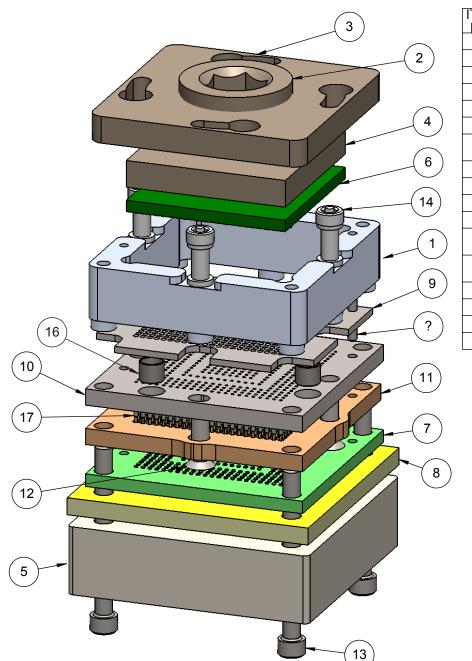
Weight: 21.11

Ironwood Package Code: BGA396D

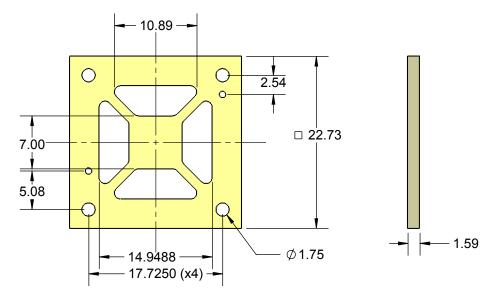


DIM	Minimum	Maximum
Α		1.40
A1	0.22	0.32
b	0.32	0.42
D	14.90	15.10
Е	14.90	15.10
D1	13.	.65 BSC
E1	13.65 BSC	
е	0.65 BSC	
Array	22 x 22	

STATUS: Released	SHEET: 3 OF 5	REV. B
ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 4:1
FILE: SBT-BGA-7009 Dwg	DATE: 2/25/2013	



NO.	DESCRIPTION	Material
1	Socket Base SBT BGA 15mm IC	7075-T6 Aluminum Alloy
2	Compression Screw M10	7075-T6 Alumium Alloy
3	Socket Lid, 15mm	7075-T6 Alumium Alloy
4	Compression Plate, 15mm x 15mm	7075-T6 Aluminum Alloy
5	SBT/CBT Ni Plated 15mm Backing Plate	7075-T6 Alumium Alloy
6	BGA396 0.65mm pitch 22x22 array 15x15mm	FR4
7	Target PCB BGA396 0.65mm pitch 22x22 array	FR4
8	Insulation Plate	FR4
9	Floating Guide	PEEK Ceramic filled
10	Middle Pogo Guide	PEEK Ceramic filled
11	Bottom Pogo pin Guide	PEEK Ceramic filled
12	#0-80, 90 deg., head pin guide screw, Peek material 5.5715mm overall Length	PEEK unfilled
13	#0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
14	#0-80 Shoulder Screw, 0.062" thread length	Stainless Steel (303)
15	Dowel pin, 1/32" X .25", SS	Chrome Stainless Steel
16	Floating Guide Spring	Alloy Steel (SS)
17	SBT Pin, SBT-BGA 0.5mm-0.8mm	



Description: Socket Material List

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-7009 Drawing



©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: n/a Finish: n/a Weight: 21.11

STATUS: Released	SHEET: 4 OF 5	REV. B
ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 3:1
FILE: SBT-BGA-7009 Dwg	DATE: 2/25/2013	

Insulation Plate Scale 2:1

Rev	Date	Initials	Description
Α	12/17/12	SH	Original
В	2/17/15		Bottom Guide changes per MP238. Middle Guide changes per MP237 R3200 was R1391, adjusted dowel pin

Description: Revisions

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SB	T-BGA-7009 Drawing
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Material: Finish: Weight:

STATUS: Released	SHEET: 5 OF 5	REV. B
ENG: S. Huang	DRAWN BY: S. Huang	SCALE: 3:1
FILE: SBT-BGA-7009 Dwg	DATE: 2/25/2013	